Isolation Voltage	V_{iso}	5000 Ŷ	Vrms
Operating Temperature	T_{opr}	-40 ~ 110	Ņ
Junction Temperature	T_j	125	Ņ
Storage Temperature	T_{stg}	-40 ~ 125	Ņ
Soldering Temperature	T_{sol}	260	Ņ
Peak pulse voltage (Ŧ= 25 Ņ ; non-repetitive,off -state)	V_{pp}	3	kV

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Parameter	Symbol	Condition	Min.	Typ.	.	. !

h w59wLbD LbCh wa! ¢Lhb

J OC S Z 2 3 B M -D6P/S /

JieJie Microelectronics Co., Ltd.

Opto Coupler

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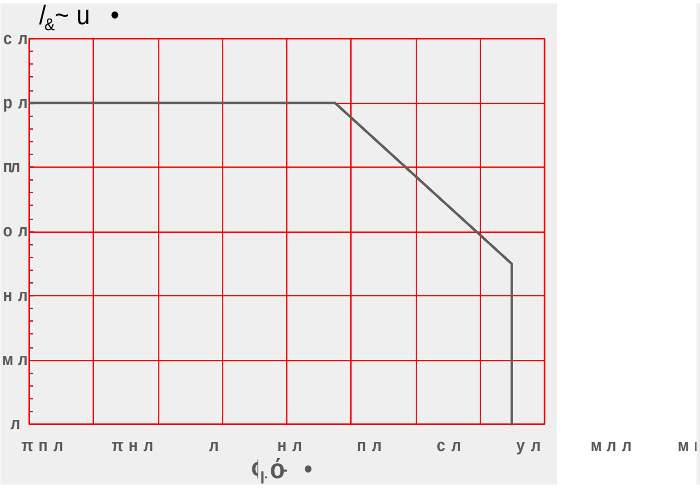

FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

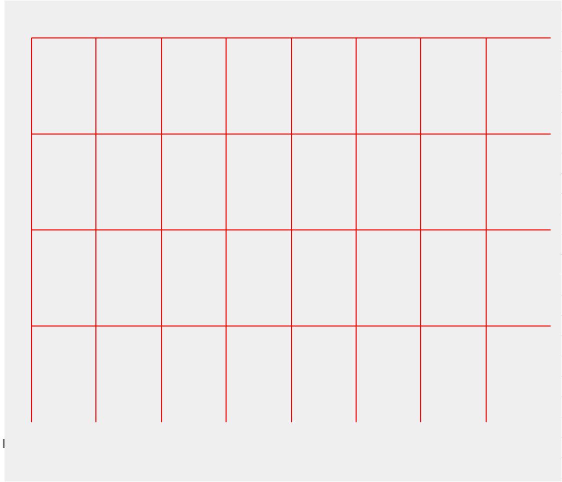

FIG.2: On-state Terminal Current vs. Ambient Temperature

FIG.7: On-state characteristics

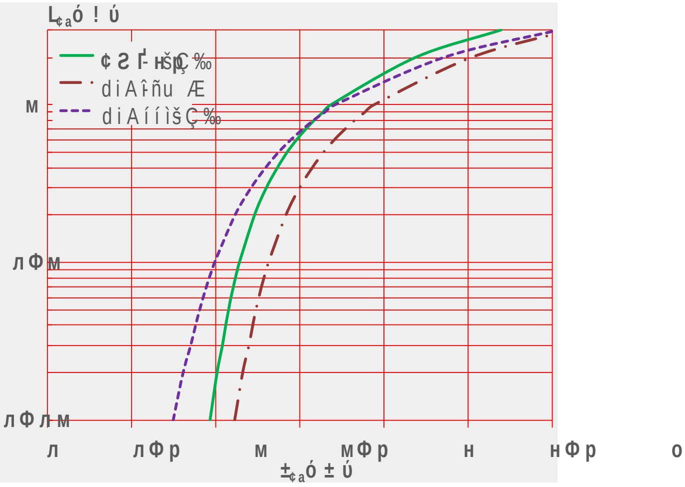

FIG.8: Normalized Holding Current vs. Ambient Temperature

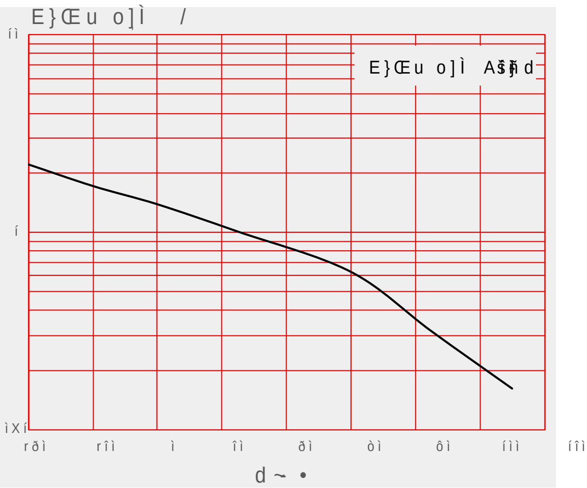

FIG.9: Turn On Time vs. Forward Current

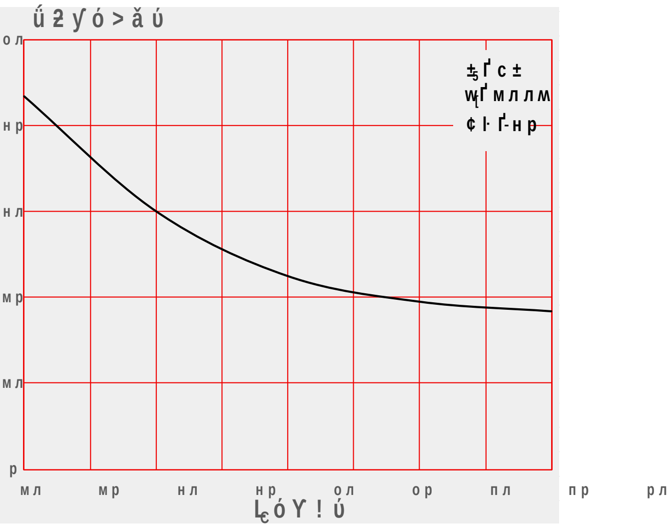

FIG.10: Normalized Inhibit Voltage vs. Ambient Temperature

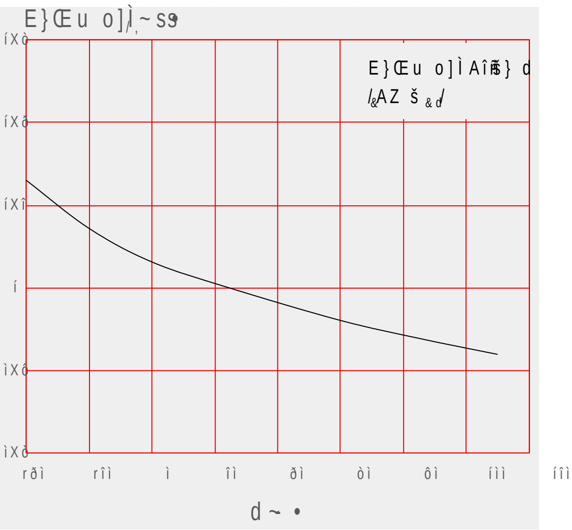

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FIG.11: Test Circuits of Turn On Time

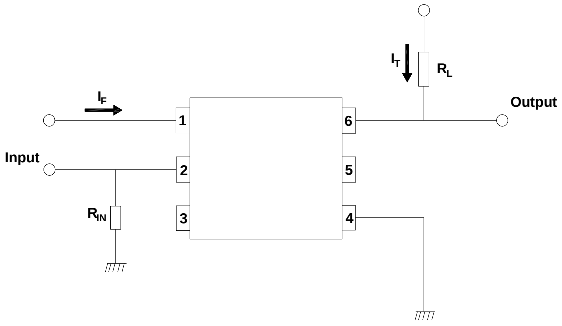
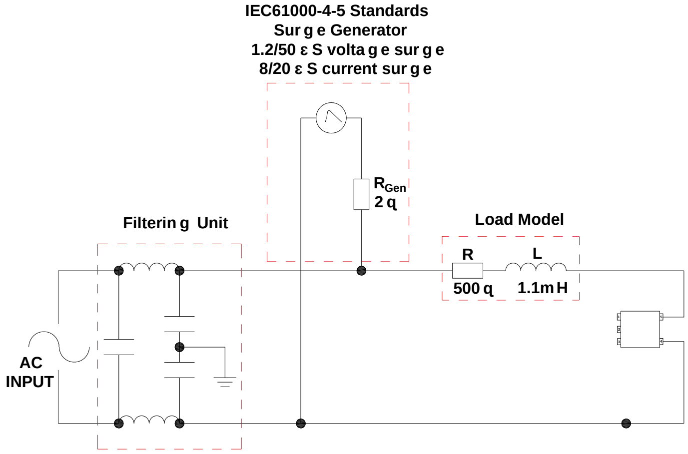


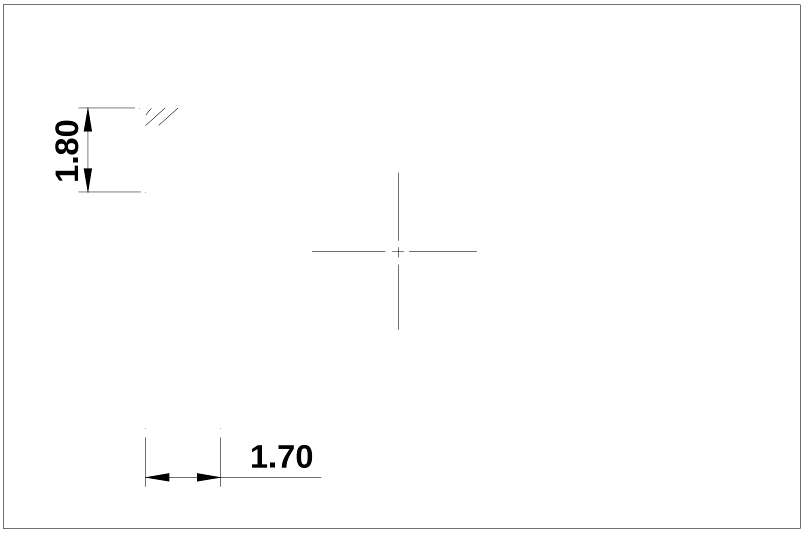
FIG.12: Wave forms of Turn On Time

FIG.13: Test circuit for inductive and resistive loads to IEC-61000-4-5 standards

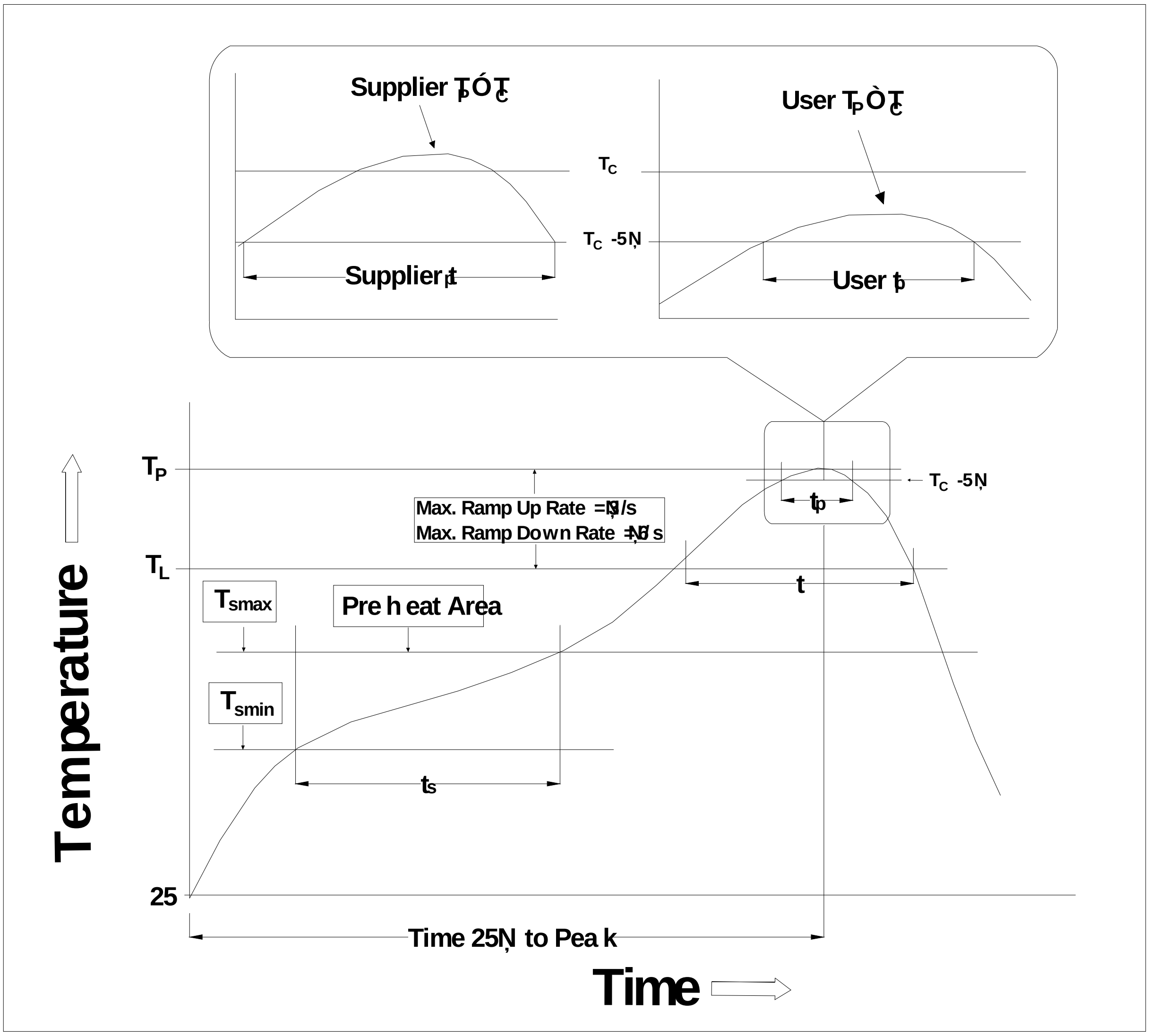


w9/h aa9b595 { h [59w a! { Y ó5ƛ Ƴ Ŝ ƴ ă ƛ ƨ ƴ ă ƛ ƴ Ƴ Ŝ Ř zú ƴ f Ŝ ă ă ƨ

Option SMD

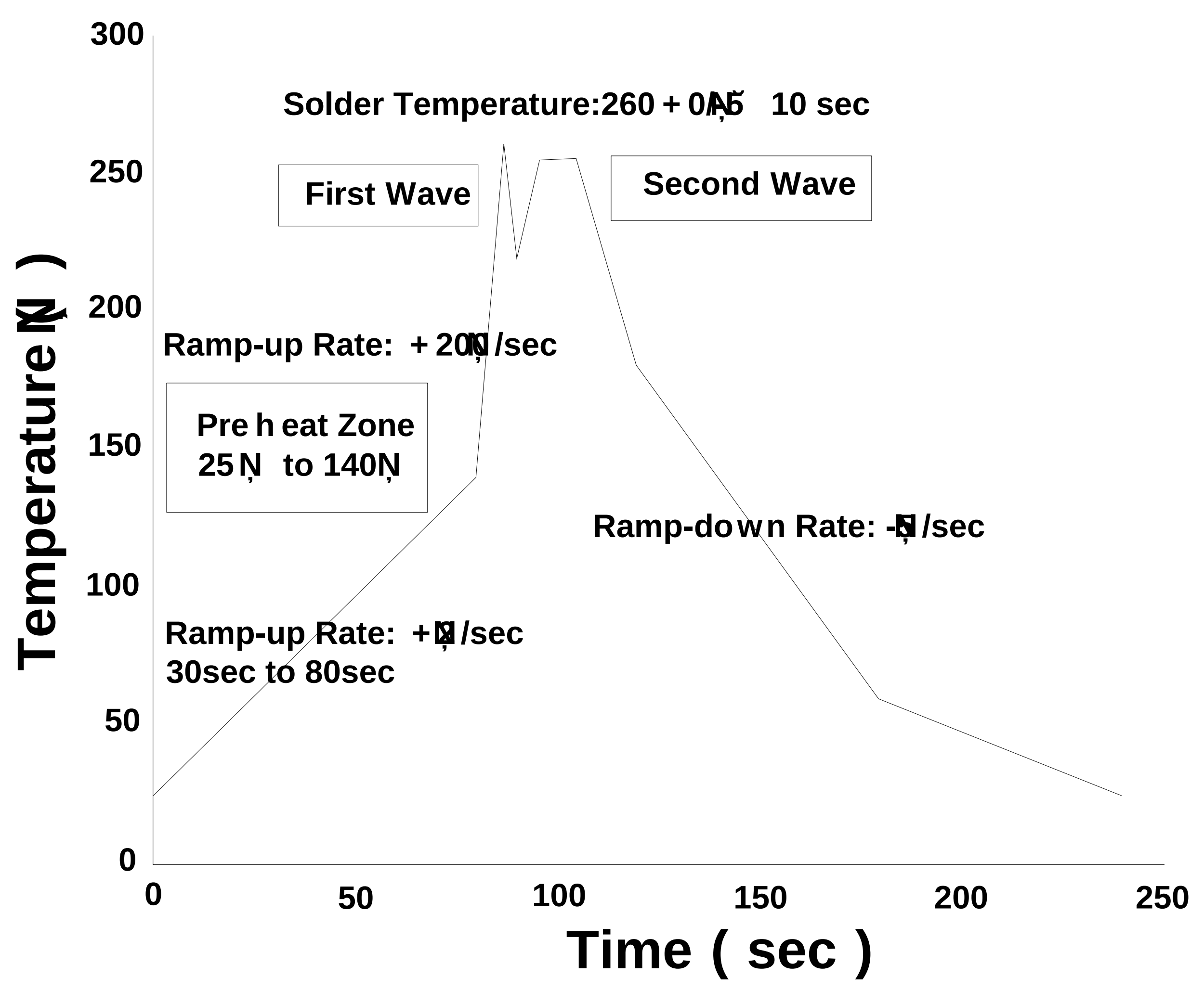


w9C[h² LbCh wa! ¢Lhb



Temperature Min. (Tsmin)	150Ņ
Temperature Max. (Tsmax)	200Ņ
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (tL to tP)	3Ņ/second max.
Liquidus Temperature (TL)	217Ņ
Time (tL) Maintained Above (TL)	60-120 seconds
Peak Body Package Temperature	260Ņ +0Ņ/-5Ņ
Time (tP) within 5Ņ of 260Ņ	10 seconds
Ramp-down Rate (TP to TL)	6Ņ/second max.

² ! ±9 { h [59wLbD



I ! b5 { h [59wLbD . ¸ { h [59wLbD Lw h b	
Soldering Temperature	360 ¤ 5Ņ
Soldering Time	3s max.

Note:

1. Reflow soldering is recommended at the temperatures and time shown, no more than three times.

2. Avoid direct contact between the epoxy body